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AS1744, AS1745

## High-Speed, Low-Voltage, Dual, Single-Supply, $4 \Omega$, SPDT Analog Switches

## 1 General Description

The AS1744/AS1745 are high-speed, low-voltage, dual single-pole/double-throw (SPDT) analog switches.
Fast switching speeds, low ON-resistance, and low power-consumption make these devices ideal for singlecell battery powered applications.

These highly-reliable devices operate from a +1.8 to +5.5 V supply, are differentiated by inverted logic, and support break-before-make switching.
With low ON-resistance (Ron), Ron matching, and Ron flatness, the devices can accurately switch signals for sample and hold circuits, digital filters, and op-amp gain switching networks.

The devices are available in a 10-pin MSOP package and a $10-$ pin TDFN package.

## 2 Key Features

- ON-Resistance:
$-4 \Omega$ (+5V supply)
- $5.5 \Omega$ (+3V supply)
- RoN Matching: $0.2 \Omega$ ( +5 V supply)
- Ron Flatness: $1 \Omega$ (+5V supply)
- Supply Voltage Range: +1.8 to +5.5 V
- 1.8V Operation:
- $9.5 \Omega$ ON-Resistance over Temperature
- 38ns Turn On Time
- 12ns Turn Off Time
- Current-Handling: 100mA Continuous
- Break-Before-Make Switching
- Rail-to-Rail Signal Handling
- Crosstalk: -90 dB at 1 MHz
- Off-Isolation: - 85 dB at 1 MHz
- Total Harmonic Distortion: 0.1\%
- Operating Temperature Range: -40 to $+85^{\circ} \mathrm{C}$
- Package Types:
- 10-pin MSOP
- 10-pin TDFN


## 3 Applications

The devices are ideal for use in power routing systems, cordless and mobile phones, MP3 players, CD and DVD players, PDAs, handheld computers, digital cameras, and any other application where high-speed signal switching is required.

Figure 1. Block Diagrams


## 4 Pinout

## Pin Assignments

Figure 2. Pin Assignments (Top View)


## Pin Descriptions

Table 1. Pin Descriptions

| Pin Number |  | Pin Name |  |
| :---: | :---: | :---: | :--- |
| AS1744 | AS1745 |  |  |
| 10 | 10 | COM1 | Analog Switch 1 Common |
| 6 | 6 | COM2 | Analog Switch 2 Common |
| 3 | 3 | GND | Ground |
| 1 | 1 | IN1 | Analog Switch 1 Logic Control Input |
| 5 | 5 | IN2 | Analog Switch 2 Logic Control Input |
| 9 | 2 | NC1 | Analog Switch 1 Normally Closed Terminal |
| 7 | 4 | NC2 | Analog Switch 2 Normally Closed Terminal |
| 2 | 9 | NO1 | Analog Switch 1 Normally Open Terminal |
| 4 | 7 | NO2 | Analog Switch 2 Normally Open Terminal |
| 8 | 8 | V+ | Input Supply Voltage. +1.8 to +5.5V |

## 5 Absolute Maximum Ratings

Stresses beyond those listed in Table 2 may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in Section 6 Electrical Characteristics on page 4 is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 2. Absolute Maximum Ratings

| Parameter | Min | Max | Units | Comments |
| :---: | :---: | :---: | :---: | :---: |
| $\mathrm{V}+$, IN1, IN2 to GND | -0.3 | +7 | V |  |
| COM $x$, NO $x$, NC $x$ to GND ${ }^{\dagger}$ | -0.3 | $\mathrm{V}+$ <br> +0.3 | V |  |
| COM $x$, NOx, NC $x$ Continuous Current | -100 | +100 | mA |  |
| COM $x$, NOx, NC $x$ Peak Current | -150 | +150 | mA | Pulsed at $1 \mathrm{~ms}, 10 \%$ duty cycle |
| Continuous Power Dissipation (TAMB $=+70^{\circ} \mathrm{C}$ ) |  | 330 | mW | Derate at $4.7 \mathrm{~mW} /{ }^{\circ} \mathrm{C}$ above $+70^{\circ} \mathrm{C}$ |
| Electro-Static Discharge |  | 1000 | V | HBM Mil-Std883E 3015.7 methods |
| Latch Up Immunity |  | 100 | mA | Norm: JEDEC 17 |
| Operating Temperature Range | -40 | +85 | ${ }^{\circ} \mathrm{C}$ |  |
| Junction Temperature |  | 150 | ${ }^{\circ} \mathrm{C}$ |  |
| Storage Temperature Range | -65 | +150 | ${ }^{\circ} \mathrm{C}$ |  |
| Package Body Temperature |  | +260 | ${ }^{\circ} \mathrm{C}$ | The reflow peak soldering temperature (body <br> temperature) specified is in accordance with <br> IPC/JEDEC J-STD-020C "Moisture/Reflow <br> Sensitivity Classification for Non-Hermetic <br> Solid State Surface Mount Devices" |

${ }^{\dagger}$ Signals on pins COM1, COM2, NO1, NO2, NC1, or NC2 that exceed $\mathrm{V}+$ or GND are clamped by internal diodes. Limit forward-diode current to the maximum current rating.

## 6 Electrical Characteristics

$V+=+4.5$ to $5.5 \mathrm{~V}, V_{I H}=+2.4 \mathrm{~V}, V I L=+0.8 \mathrm{~V}$, TAMB $^{2}=$ TMIN $^{2}$ to $T_{M A X}$ (unless otherwise specified). Typ Values @TAMB $=+25^{\circ} \mathrm{C}$.
Table 3. +5V Supply Electrical Characteristics

 Table 4. +3V Supply Electrical Characteristics

| Symbol | Parameter | Conditions |  | Min | Typ | Max | Unit |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
| Analog Switch |  |  |  |  |  |  |  |
| Vcomx VNOx, VNCx | Analog Signal Range |  |  | 0 |  | V+ | V |
| Ron | ON-Resistance | $\begin{aligned} & \mathrm{V}+=2.7 \mathrm{~V}, \mathrm{ICOM} x=10 \mathrm{~mA} \\ & \mathrm{VNO} \text { or } \mathrm{VNCx}=0 \text { to } \mathrm{V}+ \end{aligned}$ | TAMB $=+25^{\circ} \mathrm{C}$ |  | 5 | 5.5 | $\Omega$ |
|  |  |  | TAmb $=$ Tmin to Tmax |  |  | 8 |  |
| $\Delta \mathrm{RoN}$ | ON-Resistance Match Between Channels ${ }^{1}$ | $\begin{aligned} & \mathrm{V}+=2.7 \mathrm{~V}, \mathrm{ICOMx}=10 \mathrm{~mA} \\ & \mathrm{VNO} \text { or } \mathrm{VNCx}=0 \text { to } \mathrm{V}+ \end{aligned}$ | TAMB $=+25^{\circ} \mathrm{C}$ |  | 0.1 | 0.2 | $\Omega$ |
|  |  |  | TAMB $=$ TMIN to Tmax |  |  | 0.4 |  |
| Rflat(on) | ON-Resistance Flatness ${ }^{2}$ | $\begin{aligned} & \mathrm{V}+=2.7 \mathrm{~V}, \mathrm{ICOM} x=10 \mathrm{~mA} \\ & \mathrm{VNO} \text { or } \mathrm{VNCx}=0 \text { to } \mathrm{V}+ \end{aligned}$ | TAMB $=+25^{\circ} \mathrm{C}$ |  | 1.5 | 2 | $\Omega$ |
|  |  |  | TAMB $=$ Tmin to Tmax |  |  | 2.5 |  |
| INOX(OFF), INCx(OFF) | NOx or NCx OffLeakage Current ${ }^{3}$ | $\begin{gathered} \mathrm{V}+=3.3 \mathrm{~V}, \mathrm{VCOMx}=1 \text { or } 3 \mathrm{~V} \text {, } \\ \mathrm{VNO} \text { or } \mathrm{VNCx}=3 \text { or } 1 \mathrm{~V} \end{gathered}$ | TAMB $=+25^{\circ} \mathrm{C}$ | -0.1 | $\pm 0.01$ | 0.1 | nA |
|  |  |  | Tamb $=$ Tmin to Tmax | -0.3 |  | 0.3 |  |
| ICOMx(OFF) | COMx Off-Leakage Current ${ }^{3}$ | $\begin{gathered} \mathrm{V}+=3.3 \mathrm{~V}, \mathrm{VCOMx}=1 \text { or } 3 \mathrm{~V} \\ \mathrm{VNO} \text { or } \mathrm{VNCx}=3 \text { or } 1 \mathrm{~V} \end{gathered}$ | TAMB $=+25^{\circ} \mathrm{C}$ | -0.1 | $\pm 0.01$ | 0.1 | nA |
|  |  |  | TAMB $=$ TMIN to TMAX | -3 |  | 3 |  |
| ICOMx(ON) | COMx On-Leakage Current ${ }^{3}$ | $\begin{aligned} & \mathrm{V}+=3.3 \mathrm{~V}, \mathrm{VCOMx}=1 \text { or } 3 \mathrm{~V}, \\ & \mathrm{VNO} \text { or } \mathrm{VNCx}=1 \text { or } 3 \mathrm{~V} \end{aligned}$ | TAMB $=+25^{\circ} \mathrm{C}$ | -0.4 | $\pm 0.1$ | 0.4 | nA |
|  |  |  | TAMB $=$ Tmin to Tmax | -4 |  | 4 |  |
| Logic Input: (INX) |  |  |  |  |  |  |  |
| VIH | Input Logic High |  |  | 2.0 |  |  | V |
| VIL | Input Logic Low |  |  |  |  | 0.4 | V |
| ІІн,IIL | Input Leakage Current | $\mathrm{VIN} x=0$ or + | .5V | -100 | 5 | 100 | nA |
| Switch Dynamic Characteristics |  |  |  |  |  |  |  |
| ton | Turn On Time ${ }^{3}$ | VNOx or $\mathrm{VNCx}^{2}=2 \mathrm{~V}$, RLOAD $=$ $300 \Omega$, Cload $=35$ pF, Figure 12 | TAMB $=+25^{\circ} \mathrm{C}$ |  | 17 | 23 | ns |
|  |  |  | TAmb $=$ Tmin to Tmax |  |  | 28 |  |
| toff | Turn Off Time ${ }^{3}$ | $\mathrm{V}_{\mathrm{NO}} \mathrm{or} \mathrm{VNCx}^{2}=2 \mathrm{~V}$, RLOAD $=$ $300 \Omega$, Cload $=35$ pF, Figure 12 | TAMB $=+25^{\circ} \mathrm{C}$ |  | 6 | 8 | ns |
|  |  |  | TAMB $=$ Tmin to TMAX |  |  | 10 |  |
| tBBM | Break-Before-Make ${ }^{3}$ | VNOX or $\mathrm{VNCx}^{2}=2 \mathrm{~V}$, RLOAD $=$ $300 \Omega$, Cload $=35$ pF, Figure 13 | TAMB $=+25^{\circ} \mathrm{C}$ |  | 11 |  | ns |
|  |  |  | TAMB $=$ Tmin to TMAX | 1 |  |  |  |
| Q | Charge Injection | VGen $=1.5 \mathrm{~V}$, Rgen $=0$, Cload | = 1.0nF, Figure 14 |  | 0 |  | pC |
| CNOx(OFF), CNCx(OFF) | NOx, NCx OffCapacitance | VNOx or $\mathrm{VNCx}^{\text {a }}$ = GND, $\mathrm{f}=1$ | MHz , Figure 15 |  | 20 |  | pF |
| Ccomx(ON) | COMx OnCapacitance | VCOMx $=\mathrm{GND}, \mathrm{f}=1 \mathrm{MH}$ | Hz , Figure 15 |  | 56 |  | pF |
| Viso | Off-Isolation ${ }^{4}$ | $\mathrm{f}=10 \mathrm{MHz}$, RLOAD $=50 \Omega$, CLOAD $=5 \mathrm{pF}$, Figure 16 |  |  | -52 |  | dB |
|  |  | $\mathrm{f}=1 \mathrm{MHz}, \mathrm{RLOAD}=50 \Omega$, CLOA | AD $=5 \mathrm{pF}$, Figure 16 |  | -85 |  |  |
| Vст | Crosstalk ${ }^{5}$ | $\mathrm{f}=10 \mathrm{MHz}$, RLOAD $=50 \Omega$, CLO | $A D=5 \mathrm{pF}$, Figure 16 |  | -52 |  | dB |
|  |  | $\mathrm{f}=1 \mathrm{MHz}$, RLOAD $=50 \Omega$, CLOA | $A D=5 p F$, Figure 16 |  | -90 |  |  |
| Power Supply |  |  |  |  |  |  |  |
| $1+$ | Positive Supply Current | $\mathrm{V}+=3.6 \mathrm{~V}, \mathrm{VIN}=0$ or +3.6 V |  |  | 0.01 | 1.0 | $\mu \mathrm{A}$ |

1. $\Delta \operatorname{RON}=\operatorname{RON}(M A X)-\operatorname{RON}(\mathrm{MIN})$.
2. Flatness is defined as the difference between the maximum and the minimum value of ON-resistance as measured over the specified analog signal ranges.
3. Guaranteed by design.
4. Off-Isolation $=20 \log 10(\mathrm{Vcom} x / \mathrm{VNO} x), \mathrm{Vcom} x=$ output, $\mathrm{VNO}=$ input to off switch.
5. Between any two switches.

## 7 Typical Operating Characteristics

Figure 3. Frequency Response


Figure 5. Ron vs. VCOM and Temperature (VDD $=5 \mathrm{~V}$ )


Figure 7. Ron vs. Vсом


Figure 4. THD vs. Frequency


Figure 6. RON vs. VCOM and Temperature (VDD $=3 V$ )


Figure 8. ton/toff vs. Temperature ( $V+=5 \mathrm{~V}$ )


Figure 9. ton/toff vs. Supply Voltage


Figure 10. Charge Injection


## 8 Detailed Description

The AS1744/AS1745 are low ON-resistance, low-voltage, dual analog SPDT switches that operate from a single +1.8 to +5.5 V supply.

CMOS process technology allows switching of analog signals that are within the supply voltage range (GND to $\mathrm{V}+$ ).

## ON-Resistance

When powered from a +5 V supply, the low Ron ( $4 \Omega$ max) allows high continuous currents to be switched in a wide range of applications. All devices have low Ron flatness ( $1 \Omega, \max$ ) so they can meet or exceed the low-distortion audio requirements of modern portable audio devices.

## Bi-Directional Switching

Pins NOx, NCx, and COMx are bi-directional, thus they can be used as inputs or outputs.

## Analog Signal Levels

Analog signals ranging over the entire supply voltage ( $V+$ to GND) can be passed with very little change in ON-resistance (see Typical Operating Characteristics on page 6).

## Logic Inputs

The AS1744/AS1745 logic inputs (INx) can be driven up to +5.5 V regardless of the supply voltage value. For example, with a +3.3 V supply, $\mathrm{IN}+$ may be driven low to GND and high to +5.5 V . This allows the devices to interface with +5 V systems using a supply of less than 5 V .

## 9 Application Information

## Power-Supply Sequencing

Proper power-supply sequencing is critical for proper operation. The recommended sequence is as follows:

1. V+
2. $\mathrm{NO} x, \mathrm{NCx}, \mathrm{COM} x$

Always apply $\mathrm{V}+$ before applying analog signals, especially if the analog signal is not current-limited. If the above sequence is not possible, and if the analog inputs are not current-limited to less than 30 mA , add a small-signal diode as shown in Figure 11 (D1). If the analog signal can dip below GND, add diode D2. Adding these diodes will reduce the analog range to a diode-drop (about 0.7 V ) below $\mathrm{V}+$ (for D 1 ), and a diode-drop above ground (for D 2 ).
Note: Operation beyond the absolute maximum ratings (see page 3) may permanently damage the devices.

## Overvoltage Protection

ON-resistance increases slightly at lower supply voltages.
Figure 11. Overvoltage Protection Using 2 External Blocking Diodes


Adding diode D2 to the circuit shown in Figure 11 causes the logic threshold to be shifted relative to GND. Diodes D1 and D2 also protect against overvoltage conditions.
For example, in the circuit shown in Figure 11, if the supply voltage goes below the absolute maximum rating, and if a fault voltage up to the absolute maximum rating is applied to an analog signal pin, no damage will result.

Note: The supply voltage $(\mathrm{V}+)$ must not exceed the absolute maximum rating of +7 V .

## Power Supply Bypass

Power supply connections to the devices must maintain a low impedance to ground. This can be done using a bypass capacitor, which will also improve noise margin and prevent switching noise propagation from the $\mathrm{V}+$ supply to other components.

## Layout Considerations

High-speed switches require proper layout and design procedures for optimum performance.

- Reduce stray inductance and capacitance by keeping traces short and wide.
- Ensure that bypass capacitors are as close to the device as possible.
- Use large ground planes where possible.


## Timing Diagrams and Test Setups

Figure 12. Switching Time


Figure 13. Break-Before-Make Interval


Figure 14. Charge Injection


Figure 15. NOx, NCx, and COMx Capacitance


Figure 16. Off-Isolation, On-Loss, and Crosstalk


## Notes:

1. Measurements are standardized against short-circuit at all terminals.
2. Off-isolation is measured between COMx and the off $\mathrm{NCx} / \mathrm{NOx}$ terminal of each switch. Off-isolation $=$ $20 \log ($ Vout/Vin).
3. Crosstalk is measured from one channel to all other channels.
4. Signal direction through the switch is reversed; worst values are recorded.

## Package Drawings and Markings

The devices are available in a $10-\mathrm{pin}$ MSOP package and a $10-\mathrm{pin}$ TDFN package.
Figure 17. 10-pin MSOP Package


| Symbol | Typ | $\pm$ Tol | Symbol | Typ | $\pm$ Tol |
| :---: | :---: | :---: | :---: | :---: | :---: |
| A | 1.10 | Max | b | 0.23 | $+0.07 /-0.08$ |
| A1 | 0.10 | $\pm 0.05$ | b1 | 0.20 | $\pm 0.05$ |
| A2 | 0.86 | $\pm 0.08$ | c | 0.18 | $\pm 0.08$ |
| D | 3.00 | $\pm 0.10$ | c1 | 0.15 | $+0.03 /-0.02$ |
| D2 | 2.95 | $\pm 0.10$ | $\theta 1$ | $3.0^{\circ}$ | $\pm 3.0^{\circ}$ |
| E | 4.90 | $\pm 0.15$ | $\theta 2$ | $12.0^{\circ}$ | $\pm 3.0^{\circ}$ |
| E1 | 3.00 | $\pm 0.10$ | $\theta 3$ | $12.0^{\circ}$ | $\pm 3.0^{\circ}$ |
| E2 | 2.95 | $\pm 0.10$ | L | 0.55 | $\pm 0.15$ |
| E3 | 0.51 | $\pm 0.13$ | L1 | 0.95 BSC | - |
| E4 | 0.51 | $\pm 0.13$ | aaa | 0.10 | - |
| R | 0.15 | $+0.15 /-0.08$ | bbb | 0.08 | - |
| R1 | 0.15 | $+0.15 /-0.08$ | ccc | 0.25 | - |
| t1 | 0.31 | $\pm 0.08$ | e | 0.50 BSC | - |
| t2 | 0.41 | $\pm 0.08$ | S | 0.50 BSC | - |

## Notes:

1. All dimensions are in millimeters, angles in degrees, unless otherwise specified.
2. Datums $B$ and $C$ to be determined at datum plane $H$.
3. Dimensions $D$ and $E 1$ are to be determined at datum plane $H$.
4. Dimensions D2 and E2 are for top package; dimensions D and E1 are for bottom package.
5. Cross section A-A to be determined at 0.13 to 0.25 mm from lead tip.
6. Dimensions D and D2 do not include mold flash, protrusion, or gate burrs.
7. Dimensions E1 and E2 do not include interlead flash or protrusion.

Figure 18. 10-pin TDFN Package (3.0x3.0mm)



DETAILB ODD TERMINAL SIDE

| Variations |  |  |  |  |
| :---: | :---: | :---: | :---: | :---: |
| Symbol | Min | Typ | Max | Notes |
| D BSC |  | 3.00 |  | 1,2 |
| E BSC |  | 3.00 |  | 1,2 |
| D2 | 2.20 |  | 2.70 | 1,2 |
| E2 | 1.40 |  | 1.75 | 1,2 |
| L | 0.30 | 0.40 | 0.50 | 1,2 |
| N |  | 10 |  | 1,2 |
| ND |  | 5 |  | $1,2,5$ |

## Notes:

1. Dimensioning and tolerancing are compliant with ASME Y14.5M-1994.
2. Dimensions are in millimeters, angles in degrees $\left({ }^{\circ}\right)$.
3. $N$ is the total number of terminals.
4. The terminal 1 identifier and terminal numbering convention shall conform to JESD 95-1 SPP-012. Details of terminal 1 identifier are optional, but must be located within the zone indicated. The terminal 1 identifier may be either a mold, embedded metal or mark feature.
5. Dimension b applies to metallized terminal and is measured between 0.15 and 0.30 mm from terminal tip.
6. ND refers to the maximum number of terminals on $D$ side.
7. Variation shown in Figure 18 is for illustration purposes only.
8. For variation identifier dimension details, refer to the Dimensions table.
9. For a complete set of dimensions for each variation, refer to the Variations table.
10. Unilateral coplanarity zone applies to the exposed heat sink slug and the terminals.
11. For a rectangular package, the terminal side of the package is determined by:

- Type 1: Terminals are on the short side of the package.
- Type 2: Terminals are on the long side of the package.

12. Variations specified as NJR (non JEDEC registered), with an additional dash number (e.g., $-1,-2$ ) are packages currently not registered with JEDEC.
13. When more than one variations exist for the same profile height, body size (DxE), and pitch, then those variations will be denoted by an additional dash number (i.e., $-1,-2$ ) for identification. The new variations shall be created based on any or all of the following factors: terminal count, terminal length, and exposed pad sizes.

## 10 Ordering Information

The devices are available as the standard products shown in Table 5.
Table 5. Ordering Information

| Type | Description | Delivery Form | Package |
| :---: | :---: | :---: | :---: |
| AS1744G | Dual SPDT Switch | Tube | 10-pin MSOP |
| AS1744G-T | Dual SPDT Switch | Tape and Reel | $10-$-pin MSOP |
| AS1744V-T $^{\dagger}$ | Dual SPDT Switch | Tape and Reel | $10-$ pin TDFN |
| AS1745G | Dual SPDT Switch | Tube | $10-$ pin MSOP |
| AS1745G-T $^{\text {AS1745V-T }^{\dagger}}$ | Dual SPDT Switch | Tape and Reel | $10-$ pin MSOP |

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TC4W53FU(TE12L,F) 74HC2G66DC. 125 ADG619BRMZ-REEL ADG1611BRUZ-REEL7 LTC201ACN\#PBF 74LV4066DB,118
FSA2275AUMX


[^0]:    ${ }^{\dagger}$ Available upon request. Contact austriamicrosystems, AG for details.

